



CALL FOR ABSTRACTS

From Nano to Macro

Power Electronics and Packaging

European Workshop

November 26th, 2026 - TOURS, FRANCE



Building on the remarkable success of the *Power Electronics Workshop* which has been organized for the past 16 years, IMAPS-France is proud to announce the 16th edition of the *Power Electronics and Packaging Technical Workshop*.

Organized in partnership with GREMAN (UMR 7347) Polytech-Tours, and sponsored by ST-Microelectronics, CERTeM and Polytech Tours, this highly anticipated event will take in Tours, France, on **Thursday, November 26th, 2026**.

Tours is an ideal location, situated in the scenic Loire Valley, famous for its magnificent riverside castles. Please note that the entire event will be held in English. **Save the date!**

TECHNICAL COMMITTEE:

Daniel ALQUIER	GREMAN Laboratory	France	Co-chairman
Laurent BARREAU	ST Microelectronics-Tours	France	Chairman
Lars BOETTCHER	FRAUNHOFER Institute	Germany	
Cyril BUTTAY	AMPERE Laboratory	France	
Jean-Luc DIOT	PRIVATE	France	
Franck DOSSEUL	Vernon	France	Co-chairman
Guo-Quan LU	VIRGINIA TECH	USA	
Alexandre SEIGNEURIN	ST Microelectronics- Tours	France	

We invite speakers to submit abstracts relating to the following topics:

- Power management for transportation and industrial systems
- Energy harvesting systems, from nano to macro (smart grid, wind energy, photovoltaic, etc...)
- Energy conversion systems– from power to emission (lighting, ultrasonic, infrared, etc...)

These topics could be developed around several themes, such as:

- New materials and substrates dedicated to power electronics
- Thermal or thermo mechanical or regulatory constraints (RoHS regulation, REACH, etc...)
- Dedicated technologies for integration and optimisation of power systems, including passive components (weight and size reduction, yield improvement, efficiency, etc...)
- Innovative technologies, materials and processes dedicated to interconnection and packaging (die attach, bonding wire & ribbon wires, 3D power components, etc...)
- Reliability and failure modes (impacts linked to technologies, thermal constraints, radiation, etc...), predictive methods, design of experiments, reliability
- High current and high voltage or extremely high voltage: impact on packaging technologies

Presentations duration will be 25 minutes, including 5 minutes for questions and answers. The abstract submission deadline is August 31st. Please submit abstracts in English (Conference official language) and word format, including the names of the company or institution, the speaker and associated author(s), the title of the conference and an abstract of 250-600 words. Paper acceptance will be communicated on or before September 20th.

Following the first workshop day, IMAPS will organize in the evening a specific event followed by a diner.

For further information, please contact by E-mail: imaps.france@orange.fr

Web: <http://france.imapseurope.org/>

